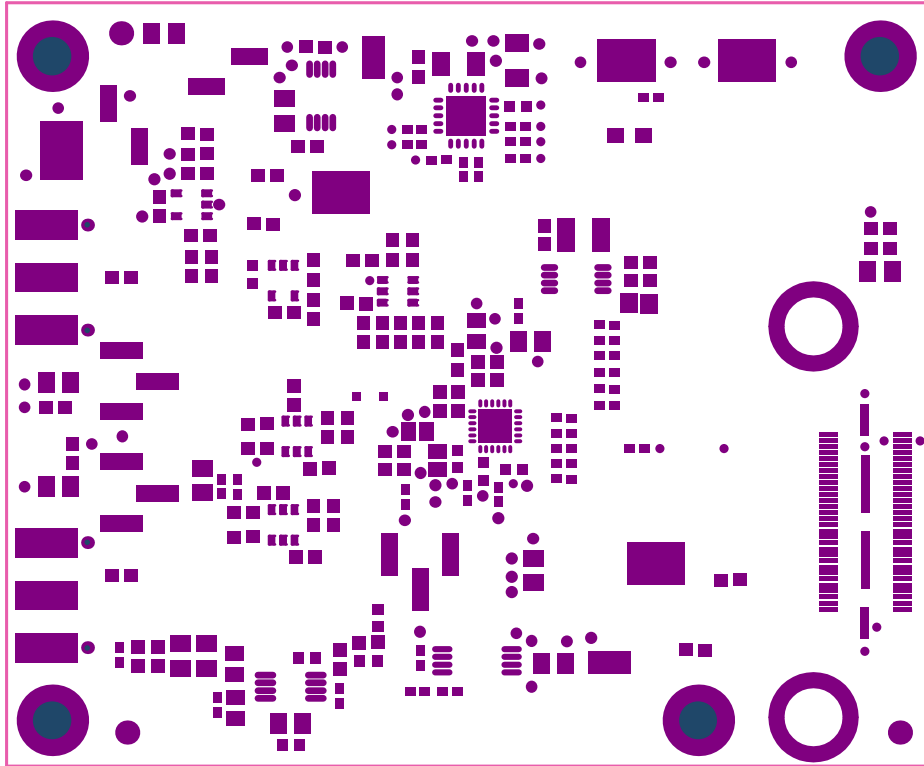
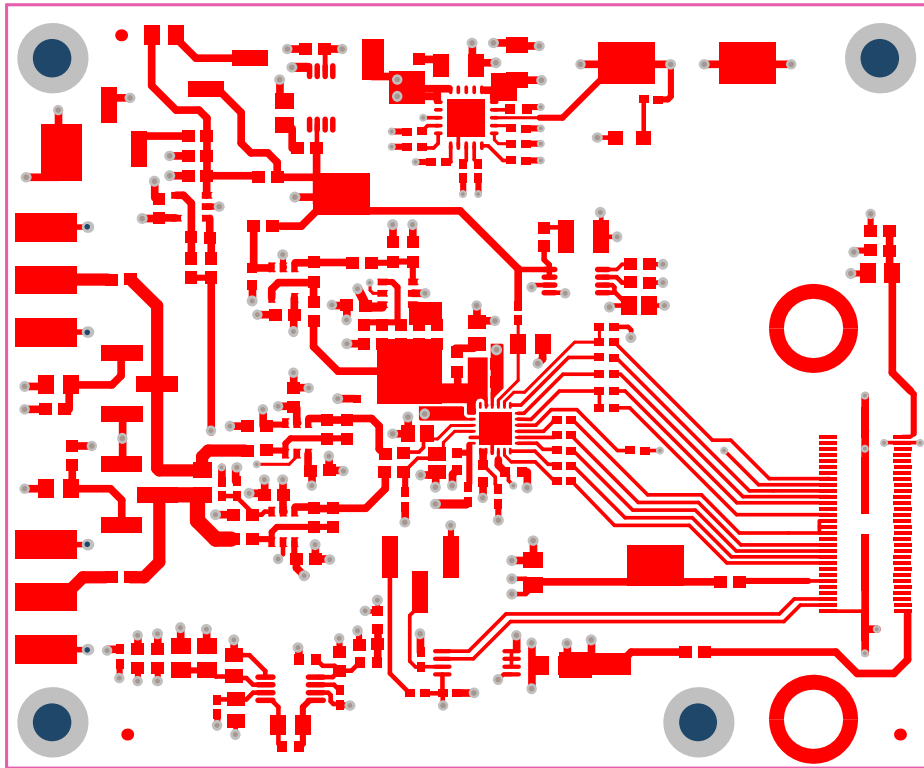


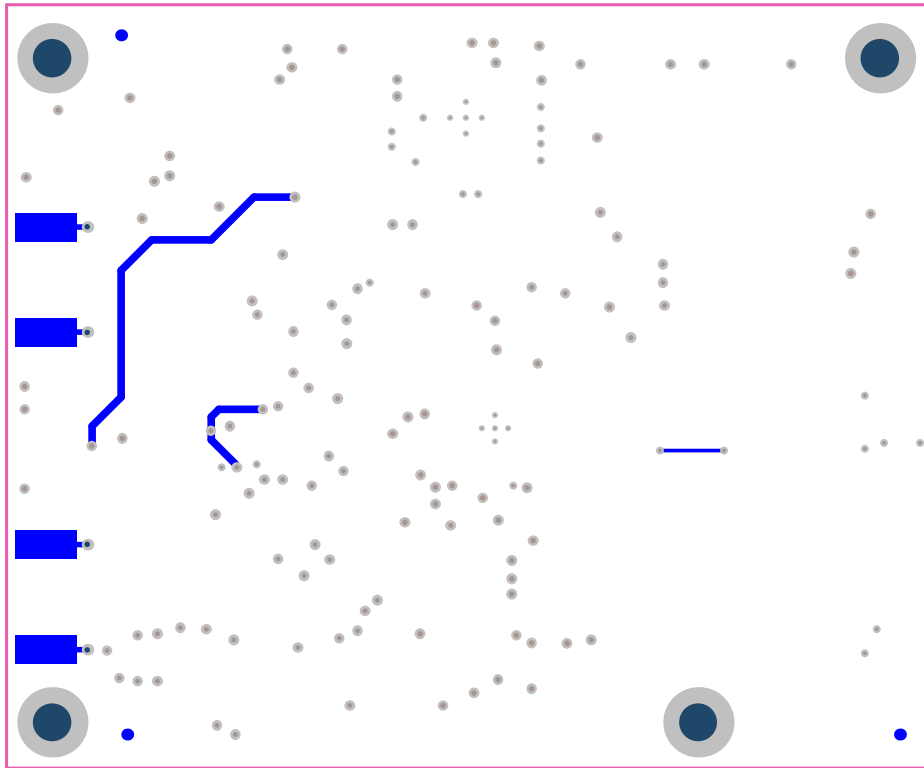
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA006	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 5/5/2016	8:52:07 AM	TEXAS INSTRUMENTS



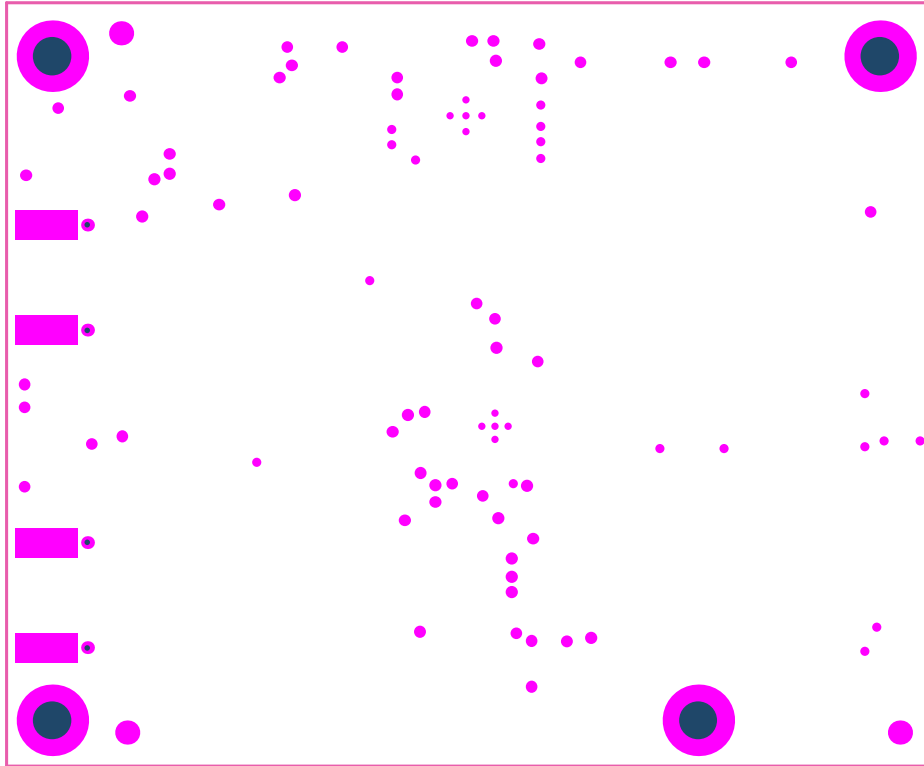
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA006	REV: C	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 5/5/2016 8:52:08 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA006	REV: C	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 5/5/2016	8:52:08 AM	TEXAS INSTRUMENTS



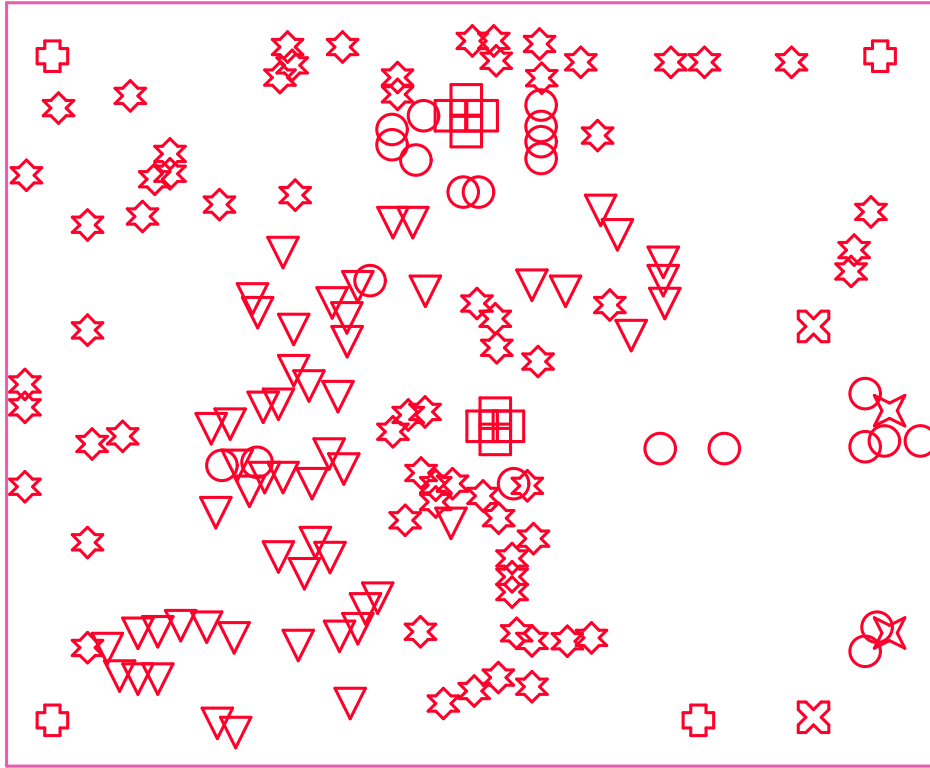
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA006	REV: C	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 5/5/2016 8:52:09 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA006	REV: C	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/5/2016 8:52:10 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA006	REV: C	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 5/5/2016 8:52:10 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✕	2	40.00mil (1.016mm)	NPTH	Round
⊠	2	173.23mil (4.400mm)	NPTH	Round
□	10	7.87mil (0.200mm)	PTH	Round
○	22	12.00mil (0.305mm)	PTH	Round
▽	56	16.00mil (0.406mm)	PTH	Round
☆	66	18.00mil (0.457mm)	PTH	Round
⊕	4	125.00mil (3.175mm)	PTH	Round
	162 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA006	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 5/5/2016	8:52:11 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA006	REV: C	SVN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 5/5/2016	8:52:11 AM	TEXAS INSTRUMENTS

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